

**Report No: MAT:AUK10S-02561**
**Issue No: 1**

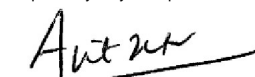
# Material Test Report

**Client:** David Rawnsley  
Waikato Chip Sealing  
PO Box 5503  
Frankton

Hamilton 3242  
NZ

**Project:** Franklin District Reseals 1011

The test results reported herein are not accredited.  
Contact the laboratory for further information. Samples  
are tested as received unless stated otherwise. This  
report may only be reproduced in full.



Approved Signatory: Ajit Thapa  
(Quality Supervisor)

Date of Issue: 26/10/10

## Sample Details

**Sample ID:** AUK10S-02561  
**Client Sample ID:** Not Applicable  
**Material:** TNZ M/6 Grade 3 Chip  
**Sample Source:** Winstones Pukekawa Quarry  
**Site/Sampled From:** WA Pukekawa Quarry  
**Date Sampled:**  
**Specification:** WDSC B301-89T  
**Sampled By:** David Rawnsley  
**Sampling Method:** As Received - Not Accredited  
**Date Tested:** 21/10/2010  
**Technician:** Ishtiaq Ahmed  
**Sampling Endorsed:** No

## Test Results

Description	Method	Result	Limits
Adhesion Agent Used	WDSC B301-89T#	Agg Bind	N/A
Adhesion Agent Dosage [pph]		0.5	N/A
Binder Type		180/200	N/A
Cutter Used			N/A
Cutter Dosage [pph]			N/A
Geological Description of Aggregate			N/A
Material Sieved Between [mm]		13.2 - 9.5mm	N/A
Sample Washed?		Washed	N/A
Test Temperature [°C]		25.0	N/A
Adhesion Set Up Period [hrs]		2.5	N/A
Adhesion Value		92	≥80
T-Value		0.7	≤2

## Comments

# The laboratory is not accredited for this test.  
Date Sampled: Unknown.

